



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-11-13
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HNRH*Z67Q81U	A	9941	2017-11-13
Amount	UoM	Unit type	ST ECOPACK Grade	
400.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
NA	NA	NA		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
RAD	6.5-10.17-3.24	2	Through hole	
Comment	Package: DO 15. MDF valid for CPs: STPS3L60QRL and STPS3L60Q			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.01	Die	25
Lead	1.44	Soft solder	3608

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	HNRH*Z67Q81U					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.548	mg	supplier	die	Silicon (Si)	7440-21-3		1.448	mg	935401	3620
				supplier	metallization	Aluminium (Al)	7429-90-5		0.060	mg	38760	150
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	646	3
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	1292	5
				supplier	Passivation	Silicon Oxide	7631-86-9		0.009	mg	5814	23
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	645	3
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	1292	5
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.010	mg	6460	21
				supplier	polymer die coating	Durimide	proprietary		0.015	mg	9690	38
				Leadframe	Copper & its alloys	286.216	mg	supplier	alloy	Copper (Cu)	7440-50-8	
supplier	alloy	Iron (Fe)	7439-89-6						6.560	mg	22920	16400
supplier	alloy	Iron Phosphide (FeP)	26508-33-8						0.395	mg	1380	988
supplier	alloy	Zinc (Zn)	7440-66-6						0.344	mg	1202	860
Soft solder	Solder	1.560	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	1.443	mg	925000	3608
				supplier	solder	Tin (Sn)	7440-31-5		0.039	mg	25000	98
				supplier	solder	Silver (Ag)	7440-22-4		0.078	mg	50000	195
Encapsulation	Other Organic Materials	104.000	mg	supplier	mold compound	Quartz	14808-60-7		81.120	mg	780000	202800
				supplier	mold compound	epoxy resin	29690-82-2		15.080	mg	145000	37700
				supplier	mold compound	phenol resin	9003-35-4		7.280	mg	70000	18200
				supplier	mold compound	Carbon Black	1333-86-4		0.520	mg	5000	1300